

FlexK-LoK Data Sheet

Low Loss, Low Dielectric Constant Silicone



LOW LOSS, LOW K DIELECTRIC MATERIAL

FlexK LoK is a low dielectric constant, low loss and low weight silicone rubber sheet for RF and microwave insulation. It weighs only about half that of polystyrene and one quarter that of polytetrafluoroethylene.

FlexK LoK is waterproof and has excellent thermal characteristics, tolerating high and low temperatures. Material does not flake or shed. Complex shape can be die cut or water jet system.

FEATURES AND BENEFITS

- Low dielectric constant
- Light weight and flexible
- Excellent thermal insulation and stability
- FlexK LoK can be used for commercial telecom and defense security

APPLICATION

- Outdoor applications / flexible radome
- Antenna mounting spacer in small electronics
- Electrical separation of components maintaining spacing
- Microwave absorber separation for PCB absorber applications
- Thin dielectric spacer

AVAILABILITY

Standard FlexK LoK sheet sizes:

- 28017002 0.010"x12.0"x12.0"
- 28017004 0.020"x12.0"x12.0"
- 28017008 0.030"x12.0"x12.0"
- 28017006 0.040"x12.0"x12.0"

SAMPLE

Standard FlexK LoK samples:

- 98100601 0.010"x4.0"x4.0"
- 98100602 0.020"x4.0"x4.0"
- 98100603 0.030"x4.0"x4.0"
- 98100604 0.040"x4.0"x4.0"

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SPECIFICATIONS

TYPICAL PROPERTIES	DATA
Thickness Range (mm +/- 15%)	0.25 – 1.0
Color	White
Dielectric Constant	1.7 +/- 5%
Dissipation Factor @ 1KHz	0.002
Dielectric Strength	102 V/mil (4 KV/mm)
Density	0.55g/cc
Elongation	10%
Tensile Strength	135 PSI minimum
Deflection	15% @ 100 PSI
Compression Set 23C, 22H / 100C, 70H	10% / 30%
Thermal Conductivity	0.11 W/mK
Temperature Range	-70°C to 177°C
Water Absorption	1.1 (% gain in 24h @ 70°F)
Outgassing ASTM E595-15	0.84% TML, 0.11% CVCM
RoHS / REACH (EU Regulation)	Compliant
Effective Frequency Range	60 Hz to 10 GHz

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